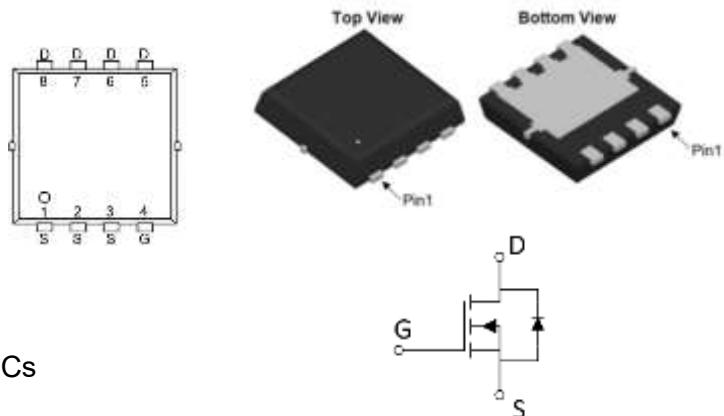


## 40V<sub>DS</sub>/±20V<sub>GS</sub> N-Channel Enhancement Mode MOSFET

### Features

- V<sub>DS</sub>=40V, I<sub>D</sub>=70A
- R<sub>DS(ON)</sub>=6mΩ (TYP.) V<sub>GS</sub>=10V
- R<sub>DS(ON)</sub>=10mΩ (TYP.) V<sub>GS</sub>=4.5V
- Reliable and Rugged
- Avalanche Rated
- Low On-Resistance
- High Current Capability

### PDFN5060



### Applications

- Load Switch
- Power management in portable/desktop PCs
- DC/DC conversion

### Ordering Information

Device	package	Device Marking	Package Qty.
HY1904C2	PDFN5060	HY1904C2	5000/PCS

### Absolute Maximum Ratings (T<sub>C</sub>=25°C,unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (V <sub>GS</sub> =0V)	V <sub>DS</sub>	40	V
Gate-Source Voltage (V <sub>GS</sub> =0V,static)	V <sub>GS</sub>	±20	V
Continuous Drain Current (T <sub>C</sub> =25°C)	I <sub>D</sub>	70	A
Continuous Drain Current (T <sub>C</sub> =100°C)		40	A
Pulsesd Drain Current	I <sub>DM</sub>	180	A
Single Pulsed Avalanche Energy	E <sub>AS</sub>	24	mJ
V <sub>DS</sub> Spike 100ns	V <sub>SPIKE</sub>	43	V
Maximum Power Dissipation (T <sub>C</sub> =25°C)	P <sub>D</sub>	54	W
Operating,Storage Temperature Range	T <sub>J,T<sub>STG</sub></sub>	-55~150	°C

### Thermal Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal Resistance,Junction-to-Case	R <sub>θJC</sub>	-	2.3	-	°C/W

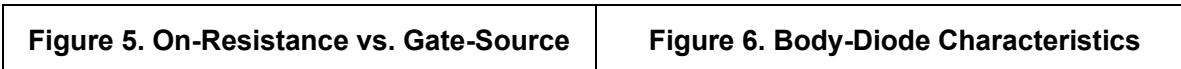
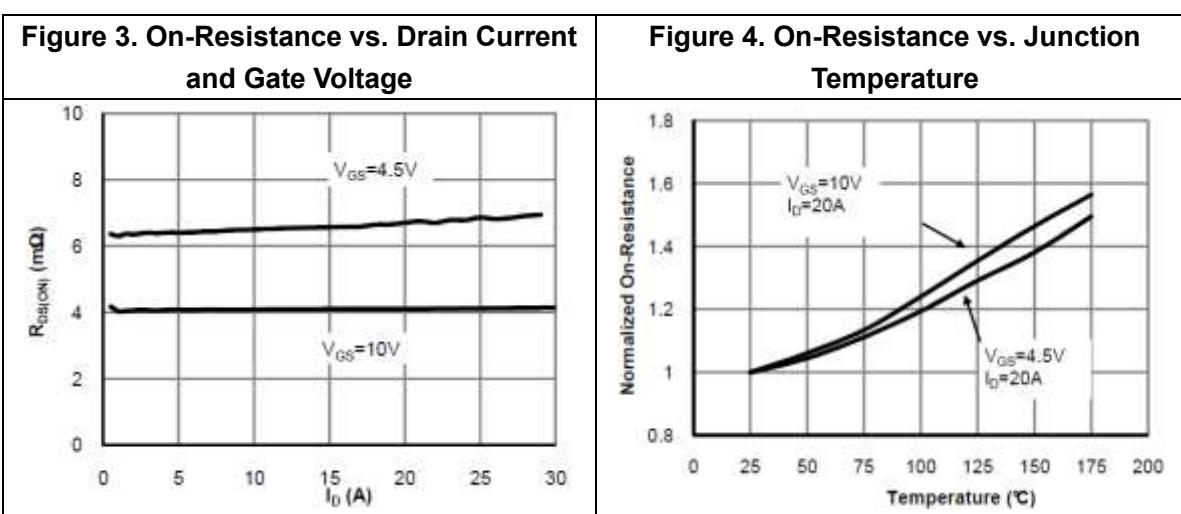
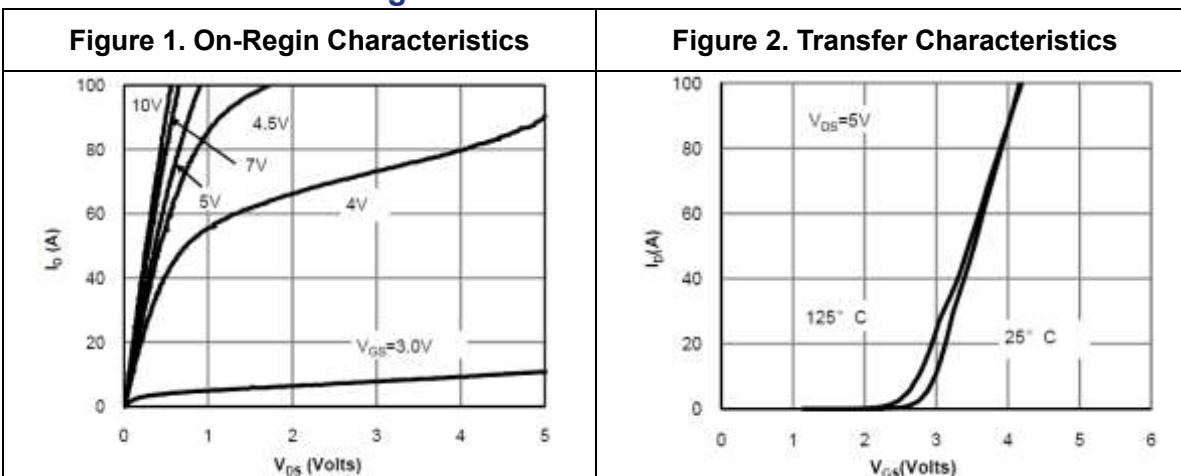
### Electrical Characteristics

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V,I <sub>D</sub> =250μA	40	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V	-	-	1	μA
Gate -Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA	1.2		2.4	V
Drain-Source On-stage Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V,I <sub>D</sub> =20A	-	5	7	mΩ
		V <sub>GS</sub> =4.5V,I <sub>D</sub> =20A	-	7	12	
Reverse Recovery Time	t <sub>rr</sub>	V <sub>GS</sub> =0V,I <sub>SD</sub> =20A	-	10.4	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>	d <sub>i</sub> /d <sub>t</sub> =500A/μs	-	13.5	-	nC

## Dynamic Characteristics

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Input capacitance	$C_{iss}$	$V_{DS}=15V$ $V_{GS}=0V$ $f=1MHz$	-	2771	-	pF
Output capacitance	$C_{oss}$		-	366	-	
Reverse transfer capacitance	$C_{rss}$		-	288	-	
Gate Resistance	$R_g$	$f=1MHz$	-	1.5	-	$\Omega$
Total Gate Charge	$Q_g$	$V_{DS}=15V$ $V_{GS}=10V$ $I_D=20A$	-	15.9	-	nC
Gate Source Charge	$Q_{gs}$		-	2.9	-	
Gate Drain Charge	$Q_{gd}$		-	3.3	-	
Turn-on delay Time	$t_{d(on)}$	$V_{GS}=10V$ $V_{DS}=15V$ $R_L=0.75\Omega$ $R_G=3\Omega$	-	6.3	-	ns
Rise time	$t_r$		-	2.7	-	
Turn-off delay Time	$t_{d(off)}$		-	18.6	-	
Fall time	$t_f$		-	4.2	-	
Body Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_{SD}=1A$	-	0.7	1	V

## Electrical Characteristics Diagrams



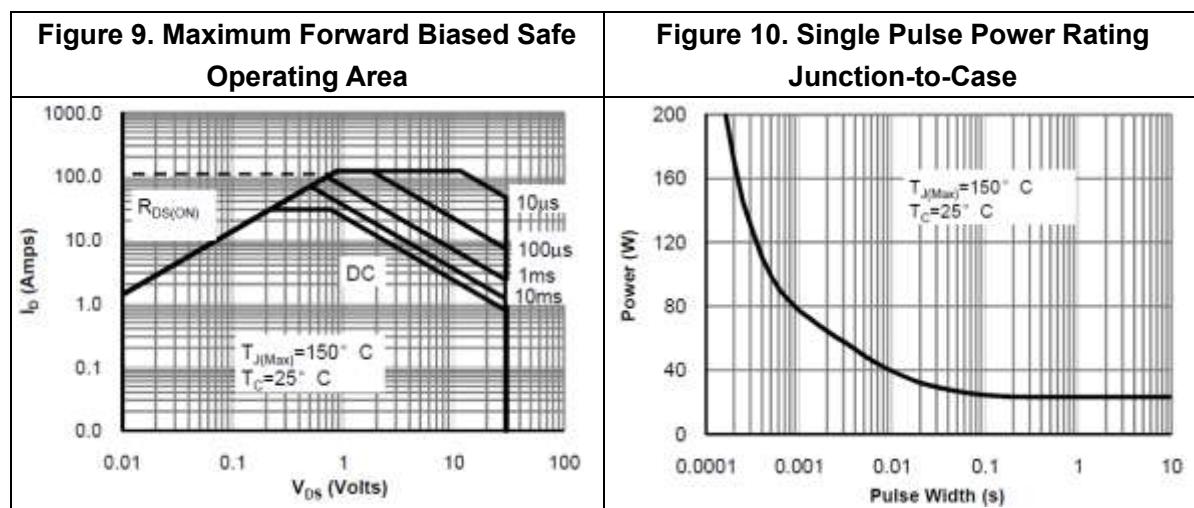
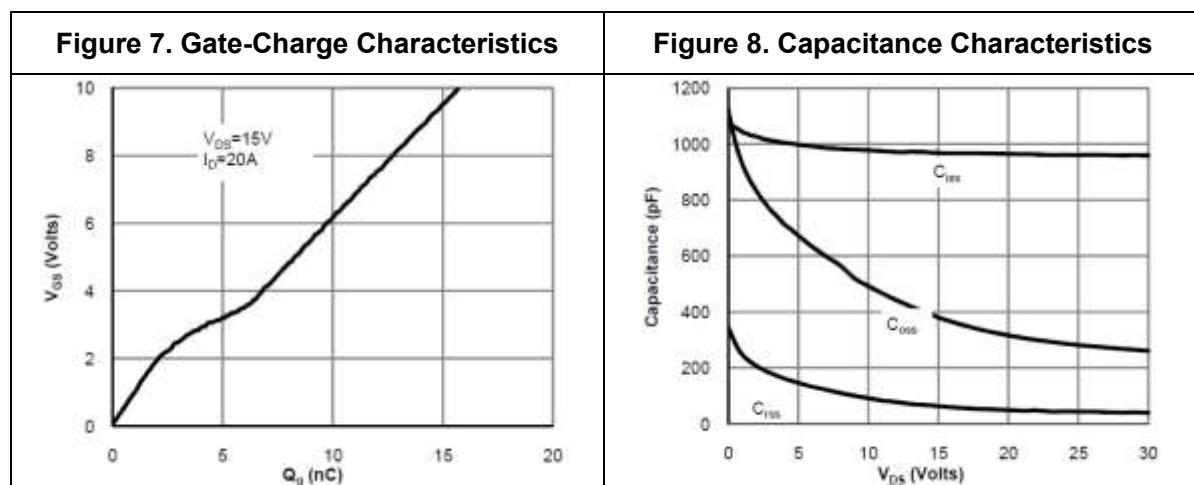
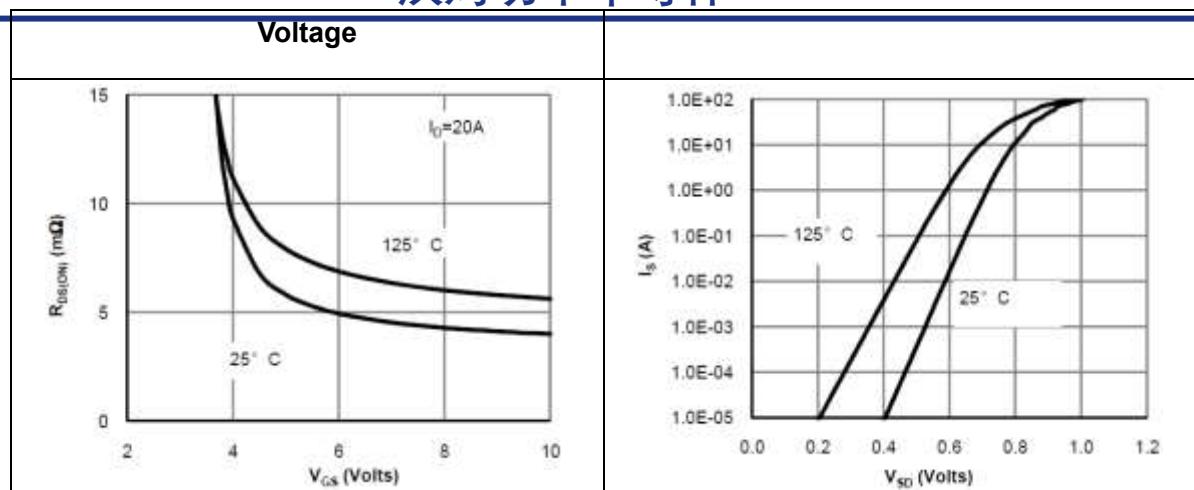
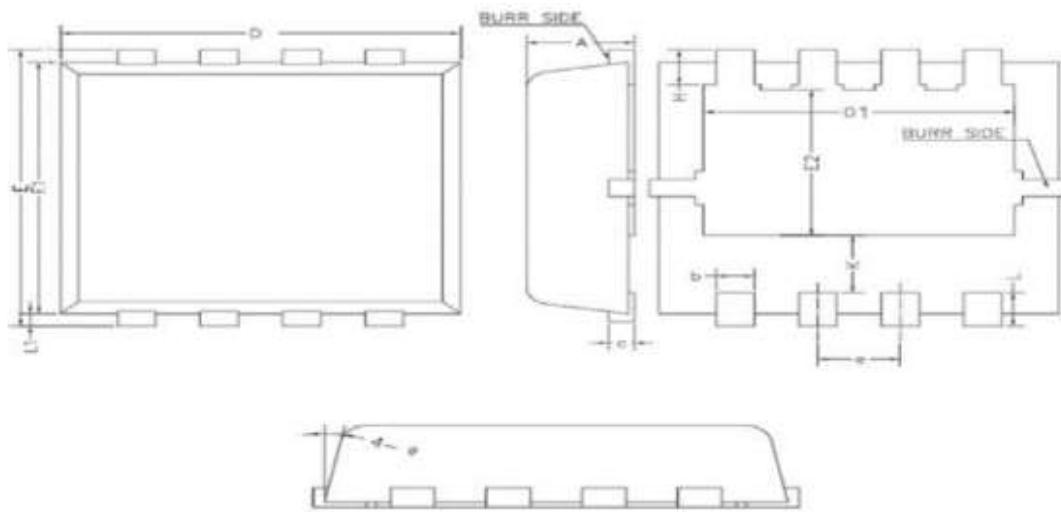
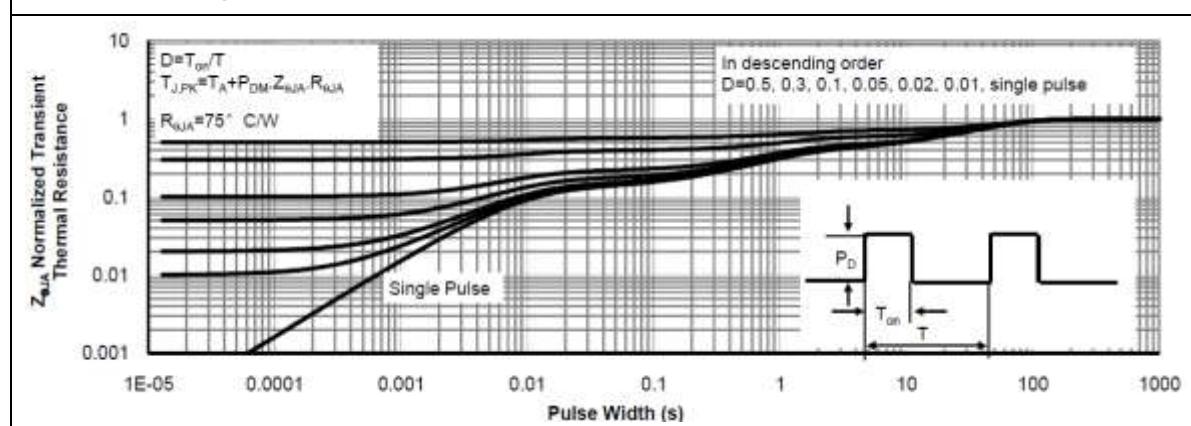


Figure 11. Normalized Maximum Transient Thermal Impedance



符号	尺寸 (mm)			符号	尺寸 (mm)		
	最小值	典型值	最大值		最小值	典型值	最大值
A	0.90	1.00	1.10	E1	5.70	5.75	5.80
b	0.33	0.41	0.51	E2	3.38	3.58	3.78
c	0.20	0.25	0.30	H	0.41	0.51	0.61
D	4.80	4.90	5.00	K	1.10	-	-
D1	3.61	3.81	3.96	L	0.51	0.61	0.71
e	1.27BSC			L1	0.06	0.13	0.20
E	5.90	6.00	6.10	$\theta$	0°	-	12°